PRELIMINARY SPEC

3.0x2.0mm SURFACE MOUNT LED LAMP

Part Number: AA3021ZGCT/E

Green



ATTENTION OBSERVE PRECAUTIONS FOR HANDLING ELECTROSTATIC DISCHARGE SENSITIVE DEVICES

Features

• 3.0mm x 2.0mm, 1.3mm high, only minimum space required.

- Suitable for compact optoelectronic applications.
- Low power consumption.
- Package : 2000pcs / reel.
- Moisture sensitivity level : level 4.
- RoHS compliant.

Description

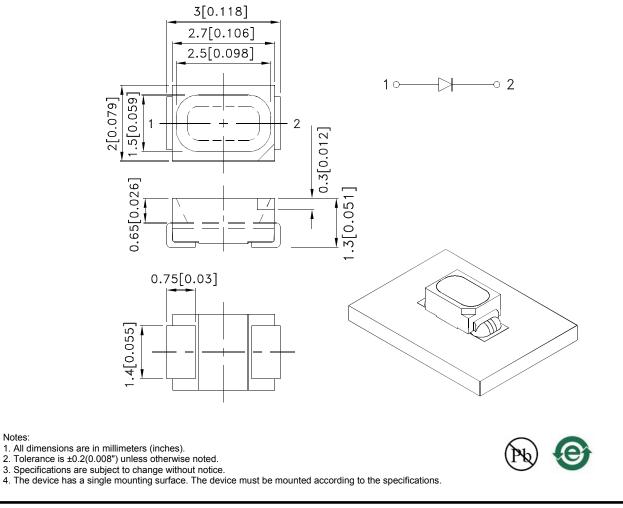
The Green source color devices are made with InGaN Light Emitting Diode.

Static electricity and surge damage the LEDS.

It is recommended to use a wrist band or anti-electrostatic glove when handling the LEDs.

All devices, equipment and machinery must be electrically grounded.

Package Dimensions



SPEC NO: DSAK1327 APPROVED: WYNEC REV NO: V.1 CHECKED: Allen Liu DATE: NOV/24/2009 DRAWN: F.F.Zhou PAGE: 1 OF 5 ERP: 1201005798

Selection Guide					
Part No.	Dice	Lens Type	lv (mcd) [2] @ 20mA		Viewing Angle [1]
			Min.	Тур.	201/2
AA3021ZGCT/E	Green (InGaN)	WATER CLEAR	900	1400	125°

Notes:

θ1/2 is the angle from optical centerline where the luminous intensity is 1/2 of the optical peak value.
Luminous intensity/ luminous Flux: +/-15%.

Electrical / Optical Characteristics at TA=25°C

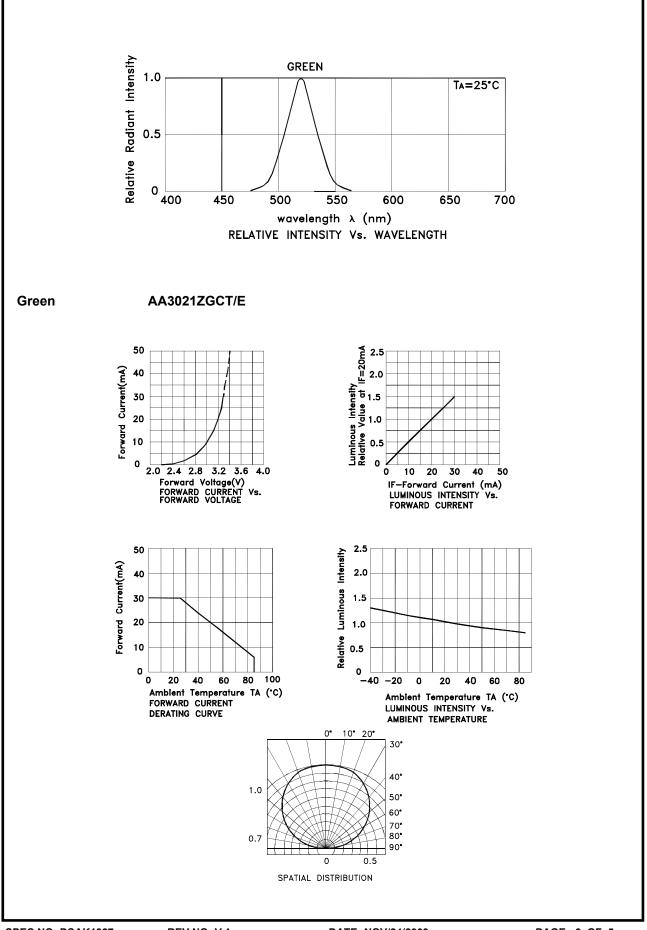
Symbol	Parameter	Device	Тур.	Max.	Units	Test Conditions
λpeak	Peak Wavelength	Green	520		nm	I⊧=20mA
λD [1]	Dominant Wavelength	Green	525		nm	I⊧=20mA
Δλ1/2	Spectral Line Half-width	Green	35		nm	IF=20mA
С	Capacitance	Green	100		pF	VF=0V;f=1MHz
VF [2]	Forward Voltage	Green	3.2	4	V	IF=20mA
lr	Reverse Current	Green		10	uA	VR=5V

Notes: 1.Wavelength: +/-1nm. 2. Forward Voltage: +/-0.1V.

Absolute Maximum Ratings at TA=25°C

Parameter	Green	Units		
Power dissipation	120	mW		
DC Forward Current	30	mA		
Peak Forward Current [1]	100	mA		
Reverse Voltage	5	V		
Operating Temperature	-40°C To +85°C			
Storage Temperature	-40°C To +85°C			

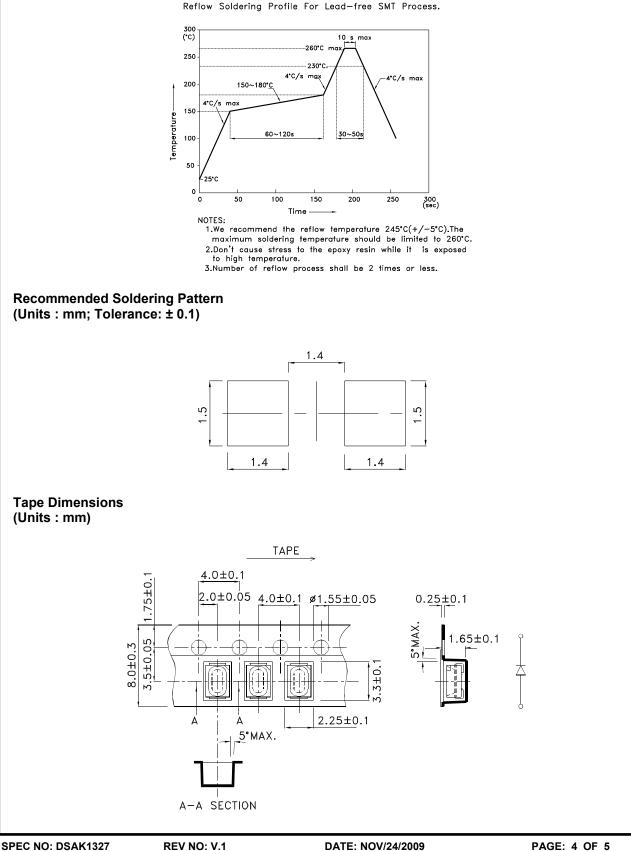
Note: 1. 1/10 Duty Cycle, 0.1ms Pulse Width.



AA3021ZGCT/E

Reflow soldering is recommended and the soldering profile is shown below. Other soldering methods are not recommended as they might cause damage to the product.

Reflow Soldering Profile For Lead-free SMT Process.



CHECKED: Allen Liu

DRAWN: F.F.Zhou

